

# **ESSCIRC/ESSDERC 2020 Presentation**

## **“Merging of photonics and micro-electronics: Photonics in the UK”**

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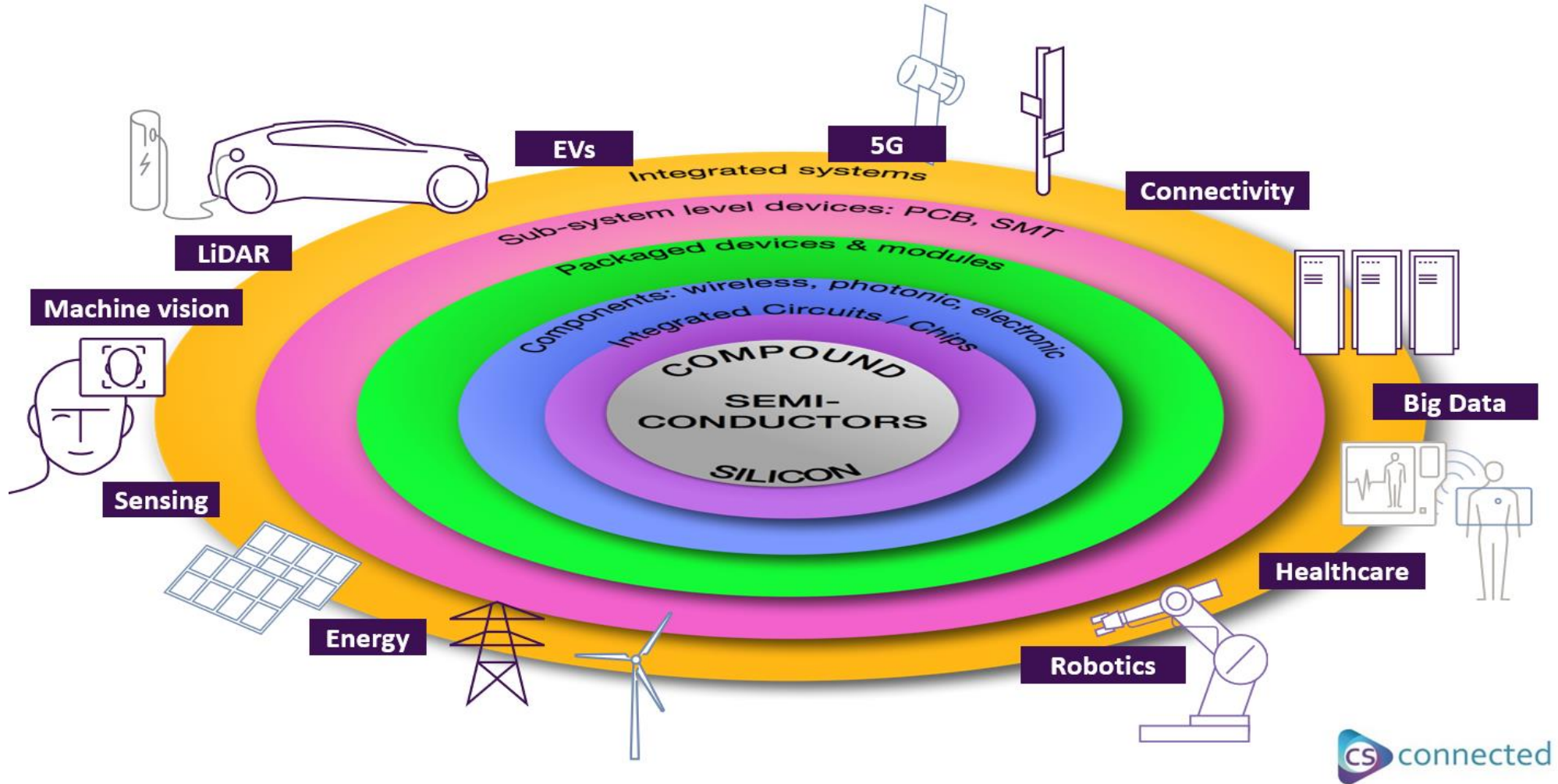


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# Global Supply Chains



# The nucleus of the Global CS Cluster in the Cardiff Capital Region

## The Entities



Institute for Compound  
Semiconductors  
£75m



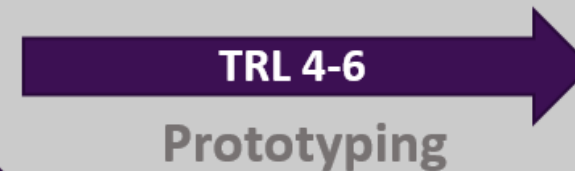
Centre for Integrated  
Semiconductor  
Materials  
£90m



Compound Semiconductor  
Centre (CSC)  
£42m



## Technology Readiness Level



IPCEI Partners

IPCEI Cooperation Partners



£50m+£100m



£40m+£80m





# The economic benefits to the region

Global CS  
Wafer & Chip  
Foundries

European CS  
Prototyping &  
Development  
Centre

Centres of  
Academic  
Excellence

Magnet for  
international  
workshops and  
conferences

Formation of  
25-50 new  
SMEs

Creation of  
2,500 to 5,000  
high value jobs  
(equivalent to  
20,000 new  
jobs)

Europe's 5<sup>th</sup> and  
newest  
Semiconductor  
Cluster

World's First  
Compound  
Semiconductor  
Cluster

# Overview of “Strength in Places” – major underpinning RD&I for IPCEI

*“The Strength in Places Fund (SIPF) will bring together research organisations, business and local leadership to drive significant economic impact, job creation and regional growth”*

UK Govt. funded



2019

Bid submission  
(£43M)

Q4  
2020

Project start

2025

5,000  
projected jobs

## 3.1: Next generation optical comms and sensing

Package includes high capacity data-centres and LIDAR sensing for autonomous vehicles.



Collaborators on RD&I for this section of the “Strength in Places” project included in this presentation



Cardiff Univ. - Active component design, modelling, prototyping (fab) and testing

CSC - Indium Phosphide epitaxial materials development

IQE - Indium Phosphide epitaxial materials scale up to 6” for volume manufacturing

NWF - passive device manufacture and PIC process devel.

Rockley Photonics - Active/passive component spec. and design, sub-system integrator to transceiver and sensor level.

# The co-integration of III-V and Si: options

Direct growth III-V epitaxy on silicon:

Defect formation (e.g. threading dislocations, antiphase domains).

Novel IQE approaches:

III-V on Ge-on-Si – novel buffer technologies to reduce TDD

Patented cREO approach on Si – rare earth oxides on <111>Si for III-V overgrowth

Wafer bonding and Transfer printing - Fabrication issues, Low light coupling efficiency.

Nanowires growth on silicon - significant progress, electrical pumped lasers challenging .

Quantum Dot (QD) offer great potential:

Less sensitivity to material defects and temperature variations.

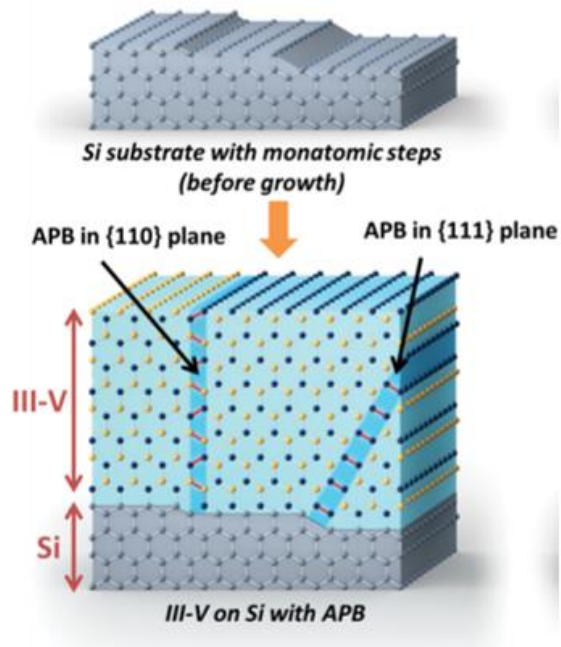
Broad optical gain spectrum.

GaAs-based 1.3 $\mu$ m InAs QD lasers grown on silicon have been achieved.

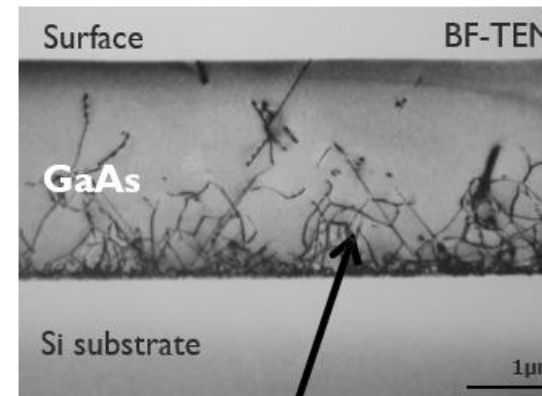
Direct growth of 1.55 $\mu$ m InAs QD lasers on silicon is difficult, but not much work done.

# III-V epitaxy on Si: fundamental challenges

- Polar/non-polar interface: Antiphase Domain(APD)
- Lattice mismatch: Misfit/threading dislocations, twins/stacking faults
- Thermal mismatch

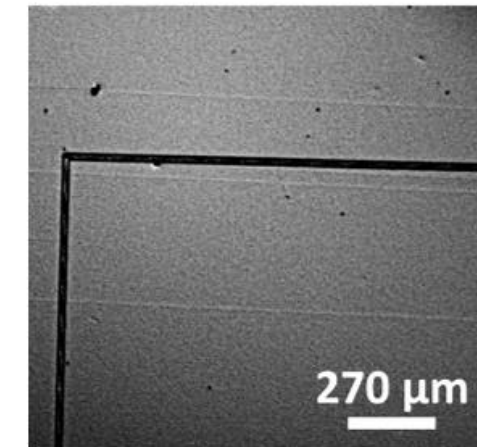
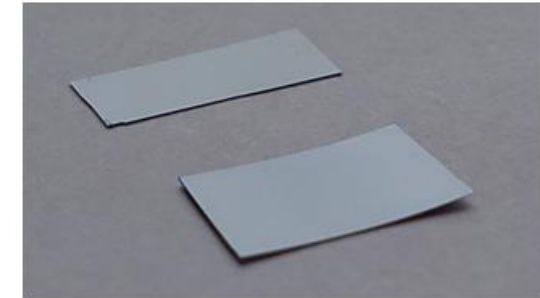


\*IEEE Spectrum



**Threading dislocation network:  
High defect density!**

\*B. Kunert, Pulse School 2015



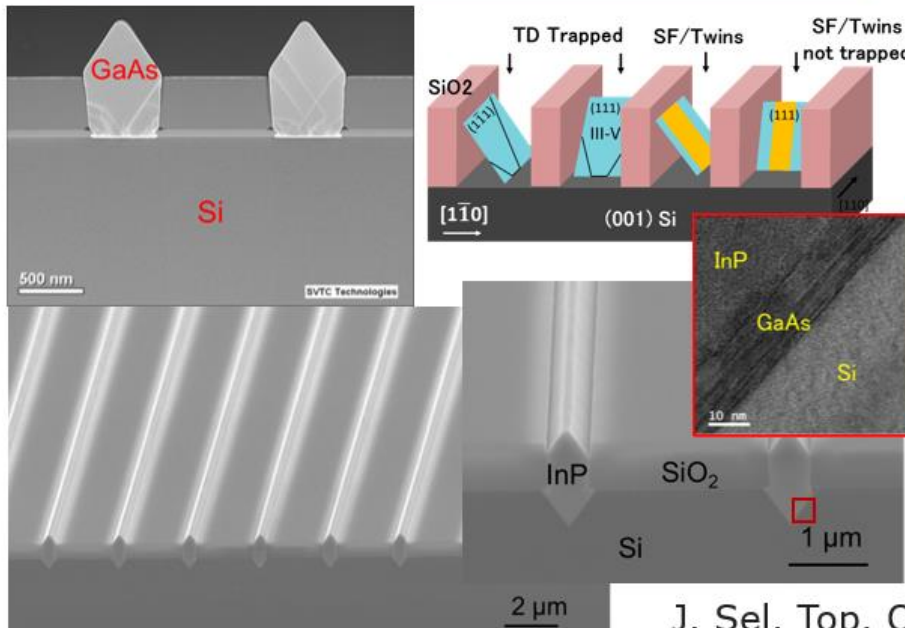
Bowing or cracking of GaAs films on Si



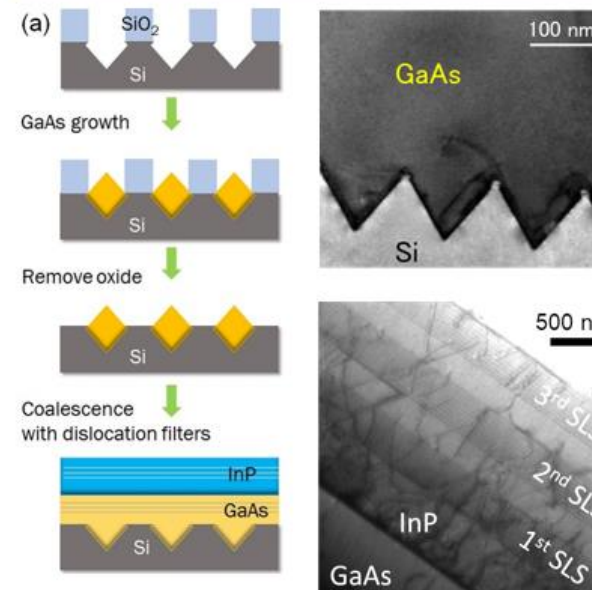
# MOCVD growth of InP on CMOS-compatible (100) Si

- GaAs/InP on V-grooved Si: Overcome Antiphase Domains, no offset Si, no Ge buffer
- Enabling low defect density nano-ridges and coalesced thin films
  - Low temperature grown GaAs stress relaxing layer (<10nm)
  - Aspect ratio trapping effect
  - Superlattices dislocation filtering layers plus thermal cycle annealing

## Aspect Ratio Trapping + V-groove epitaxy



## Coalesced V-groove epitaxy



GaAs on Si:

AFM rms < 1nm  
TDD:  $6 \times 10^6/\text{cm}^2$

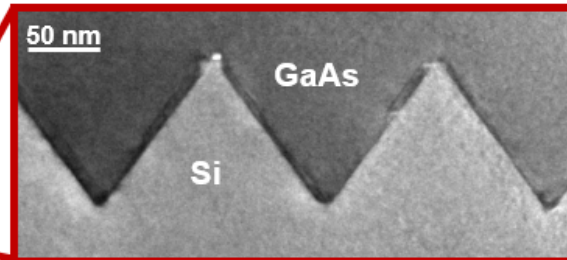
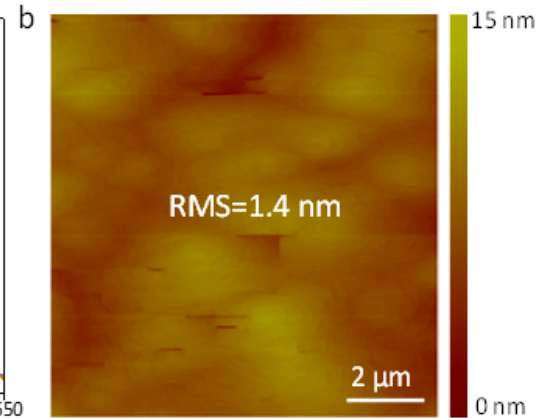
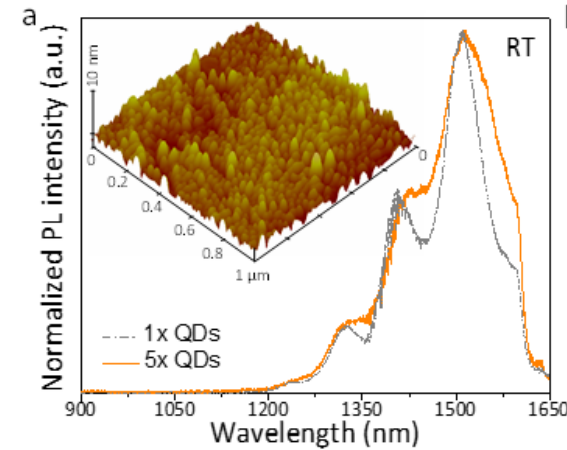
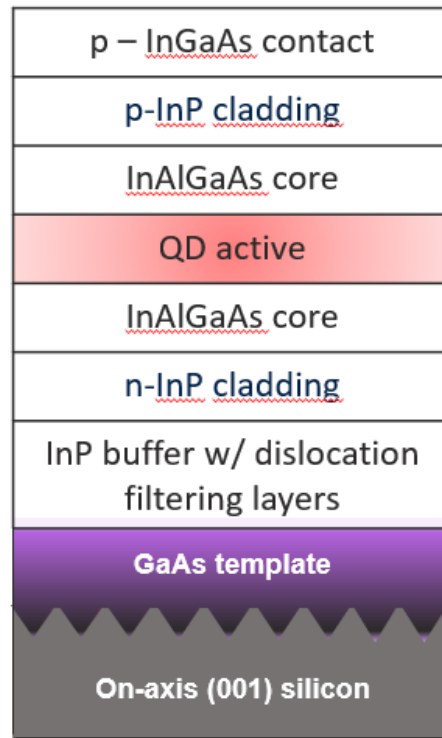
InP on Si:

AFM rms ~2nm  
TDD ~  $1 \times 10^8/\text{cm}^2$

J. Sel. Top. Quantum Electron 25, 1900711 (2019)

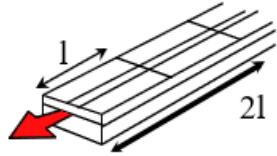


- 3x InAs quantum dot layers by MOCVD (HKUST), less sensitive to defects
  - 510 °C, 3 ML InAs, V/III=0.2
  - Dot density  $\sim 5 \times 10^{10} \text{ cm}^{-2}$  per layer

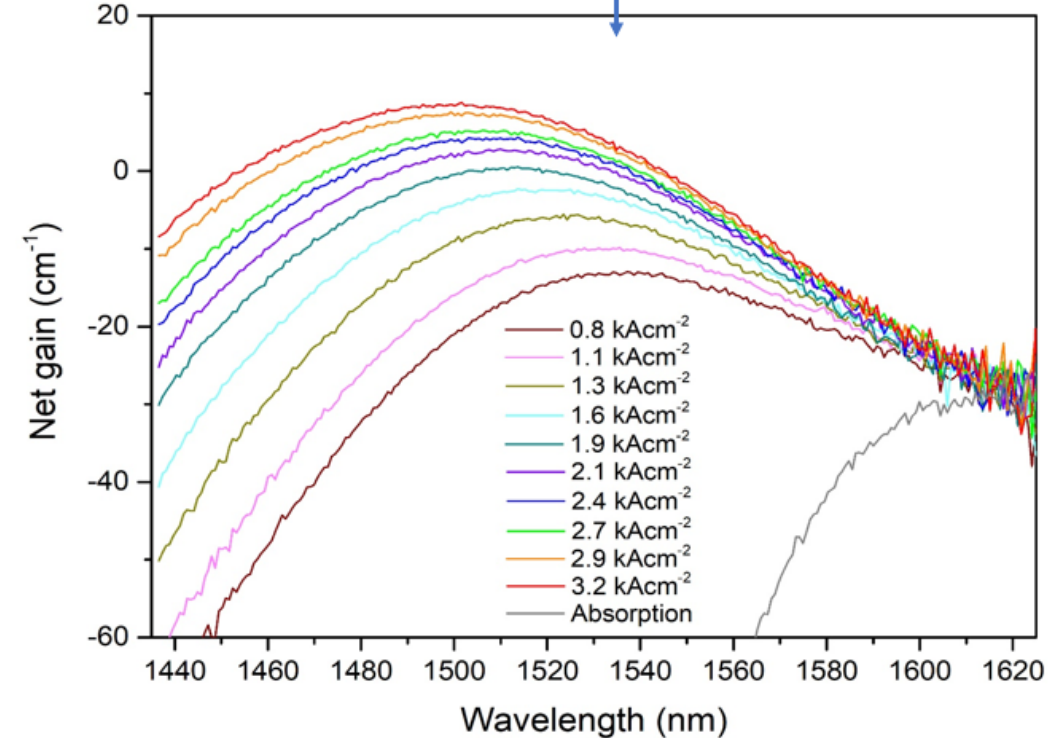
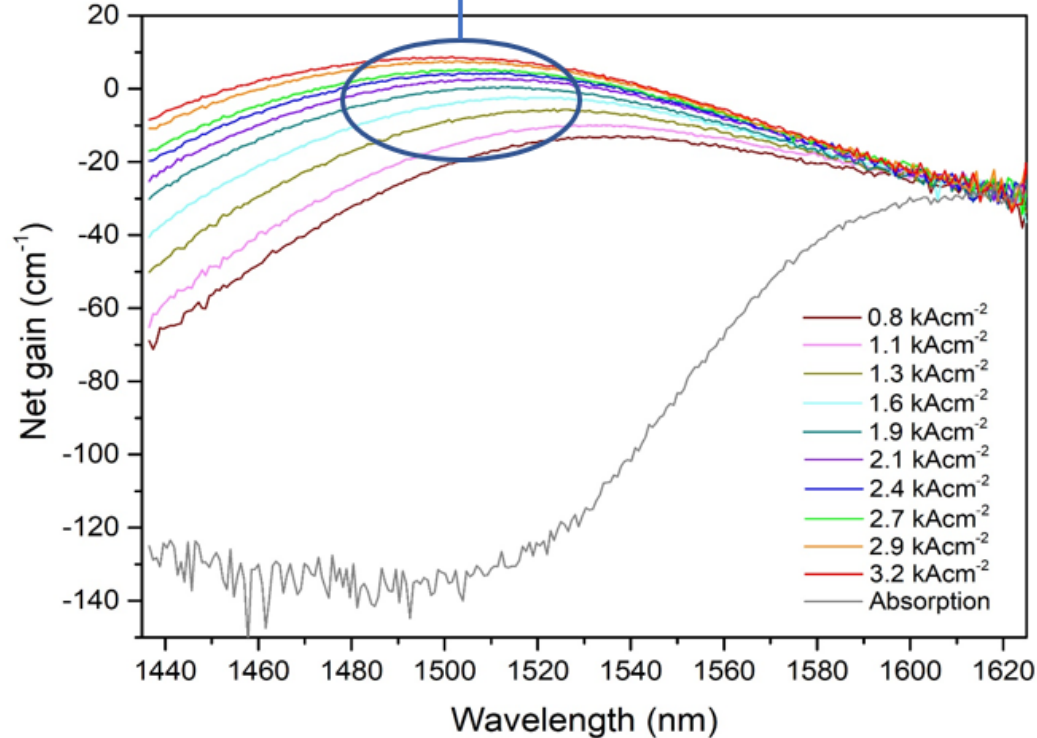


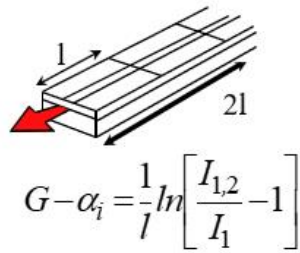
Appl. Phys. Lett. 113,  
221103 (2018)

# Basic Characterisation of InP substrate at 40°C

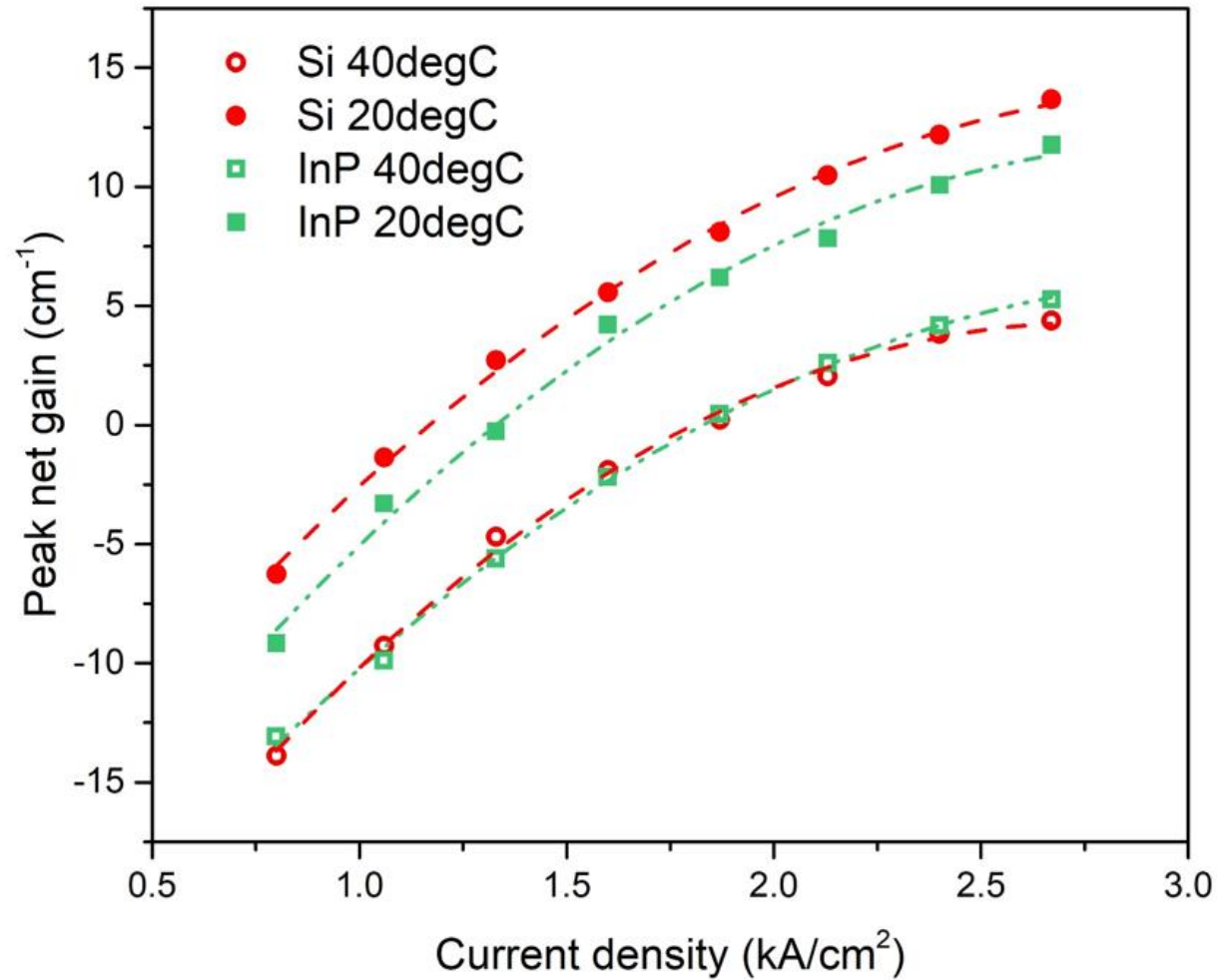


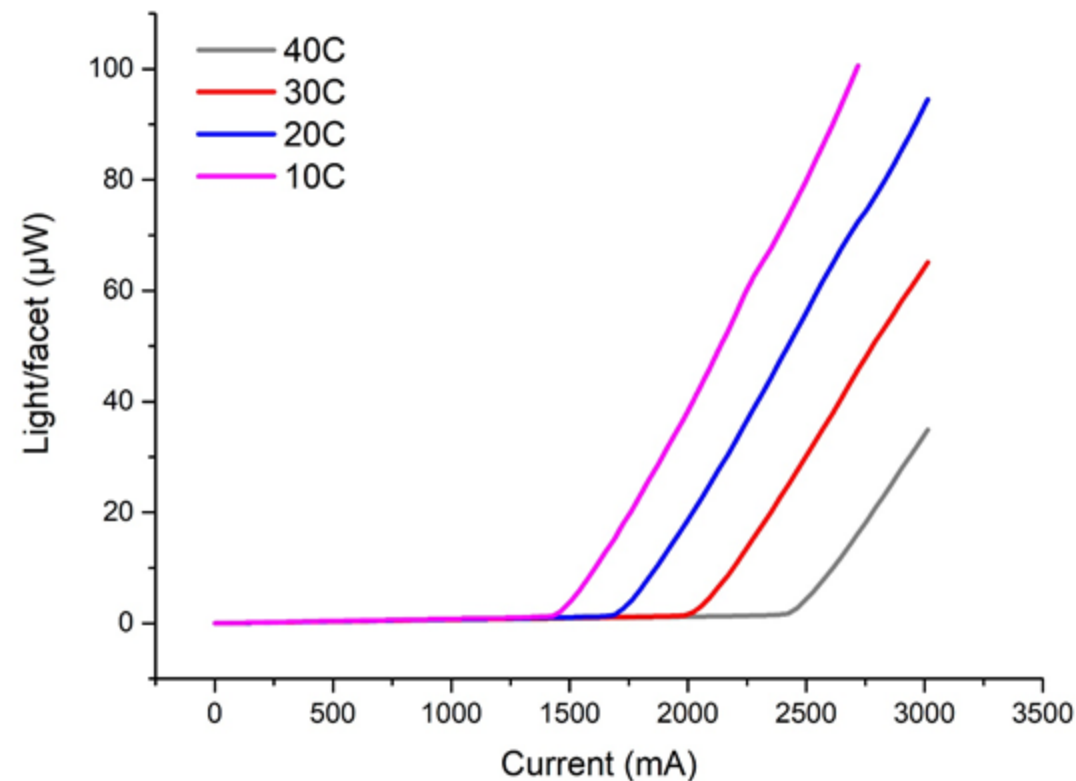
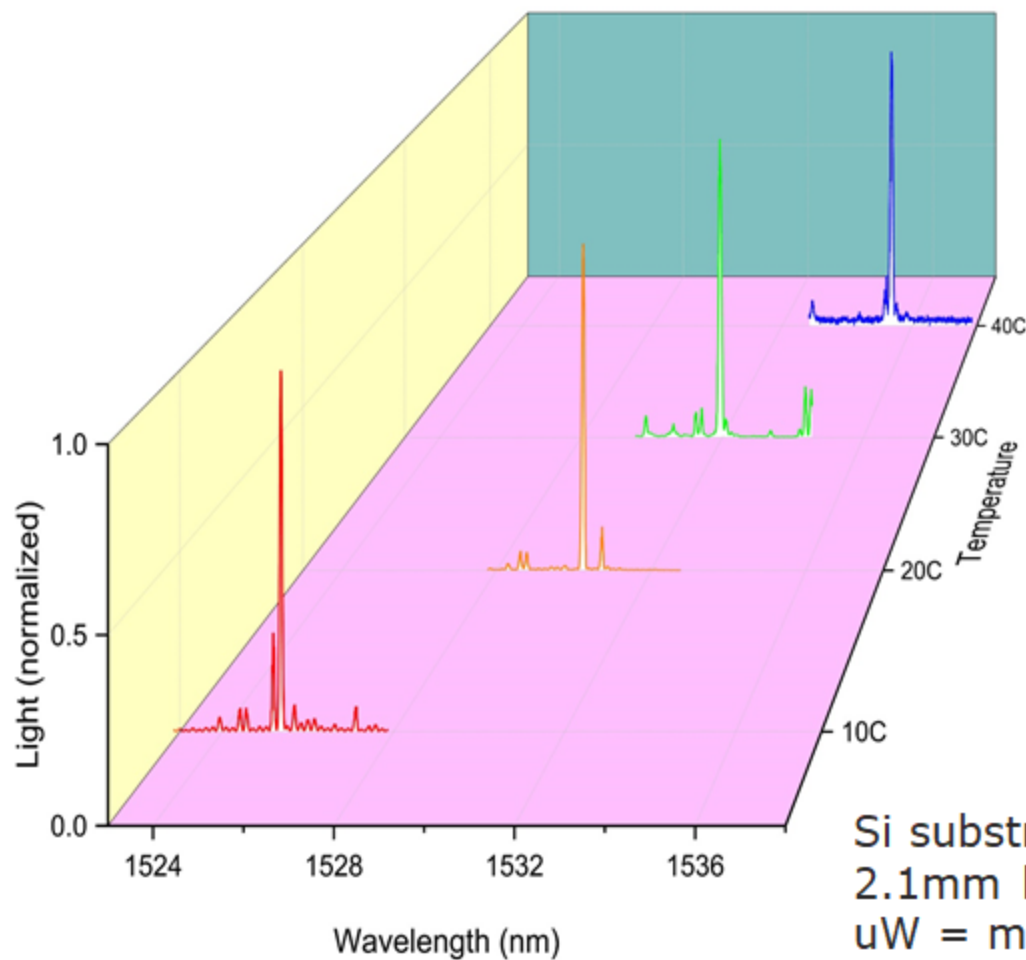
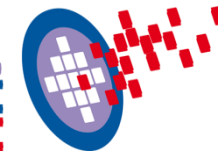
$$G - \alpha_i = \frac{1}{l} \ln \left[ \frac{I_{1,2}}{I_1} - 1 \right]$$





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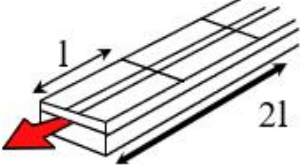




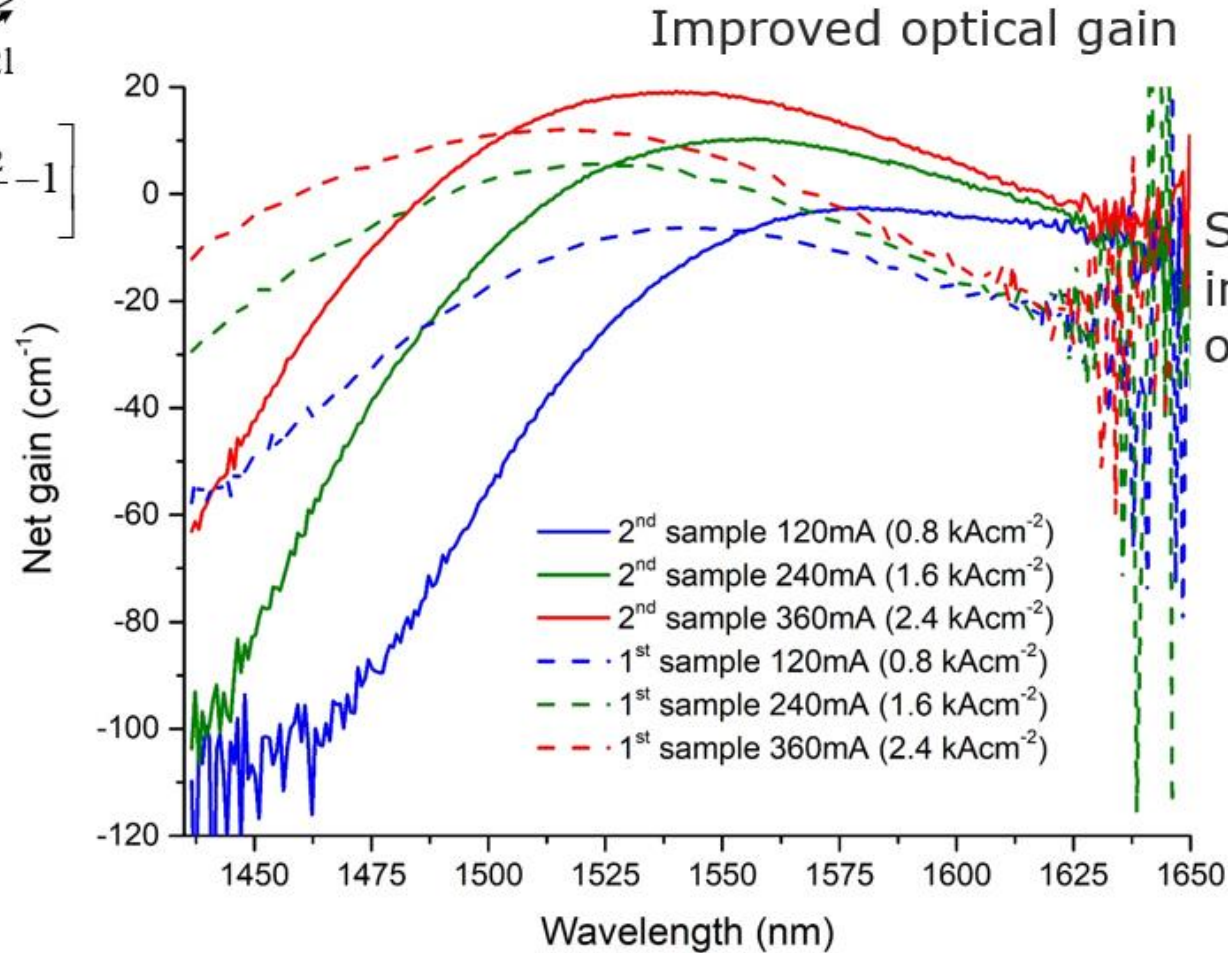
Si substrate, lasing spectra & L-I curves 10C-40C  
2.1mm long cavity, pulsed driven 0.1% duty cycle average  
uW = mW  
Lasing spectra at 10% above  $I_{th}$



# Improved waveguide design sample 2 vs sample 1



$$G - \alpha_i = \frac{1}{l} \ln \left[ \frac{I_{1,2}}{I_1} - 1 \right]$$



Significant  
improvement in  
optical loss

Initial laser results

Threshold current density  
500-700 A cm<sup>-2</sup>

1550nm wavelength

- Electrically injected 1550nm lasers grown on silicon feasible
  - further design iterations should improve performance
- Approach consistent and compatible with existing technology
- Further advances required in quantum dot technology at 1550nm and in the InP-to-Si interface

# Acknowledgements

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